## What is claimed is:

1	<ol> <li>A apparatus for measuring a gate oxide thickness,</li> </ol>
2	which is disposed in a scribe line region, comprising:
3	a first active area disposed on a substrate, a width of
4	the first active area is a predetermined width of
5	at least 2F;
6	first to fifth wordlines disposed on the substrate in
7	a first direction, with a first predetermined space
8	between each two wordlines, and the first ends of
9	the first to fifth wordlines are electrically
10	connected;
11	first and second bar-shaped trench capacitors disposed
12	under the second and the fourth wordlines
13	respectively, with a second predetermined space
14	between the first and second bar-shaped trench
15	capacitors, the first and second bar-shaped trench
16	capacitors are longer than the first active area;
17	wherein the first space is smaller than the
18	second space, and F is a minimum line width
19	of the wordlines; and
20	first and second gate structures respectively disposed
21	between the first bar-shaped trench capacitor and
22	the second wordline and between the second
23	bar-shaped trench capacitor and the fourth
24	wordline, each gate structure comprising a gate
25	conducting layer and a gate oxide layer, wherein
26	the gate conducting layers are electrically
27	connected to the wordlines respectively.

- 2. The apparatus for measuring a gate oxide thickness of claim 1, wherein the first to fifth wordlines are electrically connected to a first conducting layer.
- The apparatus for measuring a gate oxide thickness
   of claim 1, wherein the first predetermined space is the minimum
   line width F of each of the wordlines.
- 1 4. The apparatus for measuring a gate oxide thickness 2 of claim 1, wherein the width of the second predetermined space 3 is 3F.

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- 5. The apparatus for measuring a gate oxide thickness of claim 1, further comprising a second active area having a predetermined width of at least 2F, the second active area disposed on the substrate in a second direction, and the first active area is connected to the second active area by a second conducting layer.
- 6. The apparatus for measuring a gate oxide thickness of claim 1, wherein the width of the second predetermined space is 3F.
- 7. The apparatus for measuring a gate oxide thickness of claim 1, further comprising a doped layer disposed on the substrate under a second end of each wordline.
- 8. The apparatus for measuring a gate oxide thickness of claim 1, wherein the first direction and the second direction are approximately perpendicular.
  - 9. An apparatus for measuring a gate oxide thickness, which is disposed in a scribe line region, comprising:

- a first active area disposed on a substrate, a width of
  the first active area is a predetermined width of
  at least 2F;
  first to fifth wordlines disposed on the substrate in
  afirst direction, with a minimum line width F between
  - first and second bar-shaped trench capacitors disposed under the second and fourth wordlines respectively, the first and second bar-shaped trench capacitors are longer than the first active area, and with a predetermined space with 3F between the first and second bar-shaped trench capacitors;

fifth wordlines are electrically connected;

each two wordlines, and first ends of the first to

- first and second gate structures respectively disposed between the first bar-shaped trench capacitor and the second wordline and between the second bar-shaped trench capacitor and the fourth wordline, each gate structure comprising a gate conducting layer and a gate oxide layer, wherein the gate conducting layers are electrically connected to the wordlines respectively, and
- a doped layer disposed on the substrate under second ends of the first to fifth wordlines.
- 10. The apparatus for measuring a gate oxide thickness of claim 9, further comprising a second active area having a predetermined width of at least 2F, the second active area disposed on the substrate in a second direction, and the first active area is connected to the second active area by a second conducting layer. .

1	11. The apparatus for measuring a gate oxide thickness
2	of claim 9, wherein the first to fifth wordlines are electrically
3	connected to a first conducting layer.
1	12. The apparatus for measuring a gate oxide thickness
2	of claim 9, wherein the first direction and the second direction
3	are approximately perpendicular.
1	13. A gate oxide thickness measurement, comprising:
2	providing a wafer with a scribe line and a memory cell
3	area;
4	forming a measuring apparatus on the scribe line, and
5	forming a plurality of memory cells with vertical
6	transistors in the memory cell area, wherein each
7	vertical transistor has a gate oxide layer,
8	wherein the measuring apparatus comprises:
9	a first active area disposed on a substrate,
10	a width of the first active area is a
11	predetermined width of at least 2F;
12	first to fifth wordlines disposed on the
13	substrate in a first direction, with a
14	minimum line width F between each two
15	wordlines, and first ends of the first
16	to fifth wordlines are electrically
17	connected;
18	first and second bar-shaped trench capacitors
19	disposed under the second and fourth
20	wordlines respectively, the first and
21	second bar-shaped trench capacitors are
22	longer than the first active area, and

23 with a predetermined space of 3F between the first and second bar-shaped trench 24 25 capacitors; first and second gate structures respectively 26 disposed between the first bar-shaped 27 28 trench capacitor and the second wordline and between the second bar-shaped trench 29 30 capacitor and the fourth wordline, each 31 gate structure comprising conducting layer and a gate oxide layer, 32 wherein the gate conducting layers are 33 electrically connected to the wordlines 34 35 respectively; measuring a equivalent capacitance between the first 36 conducting and the first active area; 37 estimating a thickness of the gate oxide layer of the 38 measuring apparatus according to the equivalent 39 capacitance; and 40 41 estimating a thickness of the gate oxide layer of each vertical transistor according to the thickness of 42 43 the gate oxide layer of the measuring apparatus. 14. The gate oxide thickness measurement of claim 9, 1 wherein the thickness d of the gate oxide layer of the measuring 2 apparatus is obtained by a formula:  $C = \frac{\varepsilon}{d} \times A$ , wherein C is the 3 4 equivalent capacitance,  $\varepsilon$  is a dielectric constant of the gate 5 oxide layer, and A is a contact area between the gate oxide layer of the measuring apparatus and the first active area. 6